

IN THE CLAIMS:

Please cancel claim 7 without prejudice and amend claims 1, 8, 10 and 11 as shown below.

1. (amended) A semiconductor power module, comprising:
a lead frame having a first portion at a first level, a second portion surrounding the first portion at a second level, and a plurality of terminals connected to the second portion;

A1 a power circuit mounted on a first surface of the first portion;

a heat sink having an electrically insulating property and thermal conductivity, wherein the heat sink contacts a second surface opposite the first surface of the first portion of the lead frame; and

a sealer having an electrically insulating property that covers the power circuit.

A2 8. (amended) The semiconductor power module of claim 1, wherein the heat sink is adhered to at least one of the lead frame and the sealer with an adhesive.

A3 10. (amended) The semiconductor power module of claim 1, wherein the heat sink and the sealer each have grooves or rings and wherein the heat sink and the sealer are connected to each other by means of the grooves or the rings.

11. (amended) The semiconductor power module of claim 1, wherein the heat sink is sheet-shaped and comprises at least one compound selected from the group consisting of Al_2O_3 , AlN and BeO .
